Company : Taiwan Semiconductor Manufacturing Company
Company
Name : Taiwan Semiconductor Manufacturing Company
Nature Of Semiconductor

Business :
Designation

Chip Design Engineer

Tentative Job Location :

Hsinchu City, Taiwan

Responsibilities

1. Block level and top level Digital Design implementation from RTL to Physical Design, including Synthesis, DFT, DV, floorplan, CTS, P&R, Performance/Power/Area Optimization, Timing Closure, EM/IR and PV fixes, design signoff

- 2. design and sign-off methodology development and EDA flow enhancement
 3. R&D, innovation and path-finding for most advanced process challenges
 - 4. Quality infrastructure development and project/program management

 ${\bf Description:}$

 ${\bf 5.}\ \ {\bf Self\text{-}motivated,\,strong\,\,ownership\,\,and\,\,commitment,\,quick\,\,learner,\,and\,\,good\,\,teamwork}$

Requirements

 ${\bf 1. Familiar\ with\ process\ fabrication,\ CAD,\ algorithm,\ EDA\ tool,\ APR,\ timing,\ IR/EM,\ low\ power,\ physical\ verification,\ device\ modeling\ ,\ VLSI\ chip\ implementation\ or\ 3DIC}$

2. Innovative and good problem solving skills

3 Willing to learn all aspects of chip design and come up with new solutions

4. Familiar with AI/ML technology is a plus

5. Familiar with Script languages (shell, python, perl, TCL)

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| Program | AE BSBE | CE CHI | E CSE | E EE ES MI | MSI | E PHY | CHM | I MTH | I ECC | DES | IME | CGS | HSS | S EEM | I MSI | NET | PSE | Stats |
| BT | No No | No No | No | No No | No | | | | | | | | | | | | | |
| BS | | | | No | | No | No | No | No | | | | | | | | | |
| MT | No No | No No | Yes | Yes No No | Yes | | | | | | No | | | No | Yes | No | Yes | |
| DoubleMajor | r No No | No No | No | No No | No | No | No | No | No | | | | | | | | | |
| dual | No No | No No | Yes | Yes No No | Yes | No | No | Yes | No | | | | | | | | | |
| dualB | No No | No No | Yes | Yes No | Yes | No | No | Yes | No | | No | | | No | | No | Yes | |
| dualC | No No | No No | Yes | Yes No No | Yes | No | No | Yes | No | No | No | | | | | | | |
| Mdes | | | | | | | | | | No | | | | | | | | |
| MBA | | | | | | | | | | | No | | | | | | | |
| Phd | No No | No No | No | No No No | No | No | No | No | No | No | No | No | No | No | No | No | No | No |
| MSc | | | | | | No | No | Yes | | | | | | | | | | Yes |
| MSR | No No | No No | Yes | Yes No | Yes | | | | | | | No | | | | | Yes | |
| (Annual) | | | | | | | | | | | | | | | | | | |
| | BT BS MT DoubleMajordual dualB dualC Mdes MBA Phd MSc MSR | BT No No No BS MT No No DoubleMajor No No dual No No dualB No No dualC No No Mdes MBA Phd No No MSc MSR No No No Item (Annual) Master Deg | BT No No No No No BS MT No No No No No No No No dual No No No No dualB No No No No No dualC No No No No Mdes MBA No No No No MSc MSR No | BT No No No No No No BS MT No No No No No No No No No dual No | BT No No No No No No No BS No MT No | BT No No No No No No - No No No BS No | BT No BS No | BT No | BT No No No No No No No - No No | BT No No No No No No No - No No | BT No No No No No No No - No No | BT No | BT No | BT No No No No No No No No No - No No | BT No | BT No | BT No | BT No No No No No No No No - No No - No No |

Cost to Company :

| (Annual) | Master Degree | | | | | | |
|----------|---------------|--------|--|--|--|--|--|
| GROSS | \$ | 49,813 | | | | | |
| СТС | \$ | 58,913 | | | | | |

Currency: USD

1. Including 12 months base pay, 2 months Year-end bonus, 18 months Profit Sharing, Design Incentive Bonus, 2 months relocation bonus, 4-6 months sign on bonus.

Package Details:

Interview

Duration: Number of 2. Base Salary, Year-end bonus, Design Incentive Bonus are fixed and recurring. Profit Sharing is minimum amount for an average performance (i.e. top 50%) and recurring. Relocation and sign on bonus are one shot paid after onboard.

60 mins

Bond: True **CPI CutOff:** 0.0**Bond Details** 24 months Medical Requirments Resume True **Shortlist:** Resume **Shortlist** N/A Criteria: **Aptitude** False Test: Group **False Discussion: Technical False** Test: **Technical** True Interview: Technical

Techincal Interview **Rounds:** HR

Interview: HR

Interview 60 mins

Duration: Additional Information: True

1